

L21	1	(cvd or chemical adj vapor adj deposit\$4) near4 (copper cu) near2 low near temperature near8 (c! degree centigrade celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:14
L22	275	(cvd or chemical adj vapor adj deposit\$4) near4 low near temperature near8 (c! degree centigrade celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:14
L23	31	(cvd or chemical adj vapor adj deposit\$4) near2 low near temperature near2 (c! degree centigrade celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:17
L24	0	(cvd or chemical adj vapor adj deposit\$4) near2 low near temperature near2 (c! degree centigrade celsius celcius) near8 (cu or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:17
L25	0	(cvd or chemical adj vapor adj deposit\$4) near2 low near temperature near2 (c! degree centigrade celsius celcius) same (cu or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:17
L26	0	(pvd or physical adj vapor adj deposit\$4) near2 low near temperature near2 (c! degree centigrade celsius celcius) same (cu or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:18
L27	42	(pvd or physical adj vapor adj deposit\$4) near8 (c! degree centigrade celsius celcius) near4 (cu or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:22
L28	55	(electrolytic) near8 (degree centigrade celsius celcius) near4 (cu or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:23
L29	3330	((438/623) or (438/725) or (438/780) or (438/781) or (438/783)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/05 18:44

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	548659	poly(phenylene) or poly near2 phenylene	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:12
L2	4	"20030004218".pn. "20030218253".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:12
L3	4	2 and (heat\$4 thermal\$4 anneal\$4 rta rtp decompos\$4 breakdown break\$4 evaporat\$6 dissociat\$4 dissolv\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:15
L4	4538753	(heat\$4 thermal\$4 anneal\$4 rta rtp)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:15
L5	2254497	(decompos\$4 breakdown break\$4 evaporat\$6 dissociat\$4 dissolv\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:15
L6	879	porogen	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:15
L7	41	6 near4 5 near4 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:20
L8	20	7 and (@ad < "20021121")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:20
L9	3880064	remov\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:19
L10	66	6 near4 9 near4 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:20

L11	42	10 and (@ad < "20021121")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:29
L12	216432	(cvd or deposit\$4) near4 (metal copper cu aluminum al!)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:31
L13	23	11 and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:32
L14	11791	(cvd or deposit\$4) near4 (metal copper cu aluminum al!) near4 (c! degree centigrade temperature celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:33
L15	0	11 and 14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:33
L16	56400	(cvd or deposit\$4) near4 (metal copper cu aluminum al!) same (c! degree centigrade temperature celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:49
L17	10	11 and 16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:33
L18	660	(cvd or deposit\$4) near2 (copper cu) near2 (c! degree centigrade temperature celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 17:51
L19	56	(cvd or chemical adj vapor adj deposit\$4) near2 (copper cu) near2 (c! degree centigrade temperature celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:13
L20	1	(cvd or chemical adj vapor adj deposit\$4) near2 (copper cu) near2 low near temperature near8 (c! degree centigrade celsius celcius)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 18:14